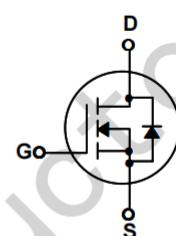


Features

- Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Extended Safe Operating Area
- Unrivalled Gate Charge : $Q_g = 13\text{nC}$ (Typ.)
- $\text{BV}_{\text{DSS}}=800\text{V}, \text{ID}=3\text{A}$
- $R_{\text{DS(on)}} : 5 \Omega$ (Max) @ $\text{VG}=10\text{V}$
- 100% Avalanche Tested



TO-220F



TO-220F

G-Gate,D-Drain,S-Source

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	3N80C	Units
V_{DSS}	Drain-Source Voltage	800	V
I_D	Drain Current -continuous ($T_c=25^\circ\text{C}$)	3	A
	-continuous ($T_c=100^\circ\text{C}$)	1.9	A
V_{GS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Plused Avalanche Energy (Note1)	320	mJ
I_{AR}	Avalanche Current (Note2)	3	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	39	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 ~ +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max	Units
$R_{\theta\text{JC}}$	Thermal Resistance,Junction to Case	--	3.2	$^\circ\text{C}/\text{W}$
$R_{\theta\text{CS}}$	Thermal Resistance,Case to Sink	0.5	--	$^\circ\text{C}/\text{W}$
$R_{\theta\text{JA}}$	Thermal Resistance,Junction to Ambient	--	62.5	$^\circ\text{C}/\text{W}$

Electrical Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250 \mu\text{A}, V_{GS}=0$	800	--	--	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D=250 \mu\text{A}$, Reference to 25°C	--	0.9	--	$\text{V}/^\circ\text{C}$
IDSS	Zero Gate Voltage Drain Current	$V_{DS}=800\text{V}, V_{GS}=0\text{V}$	--	--	10	μA
		$V_{DS}=640\text{V}, T_c=125^\circ\text{C}$			100	μA
IGSSF	Gate-body leakage Current, Forward	$V_{GS}=+30\text{V}, V_{DS}=0\text{V}$	--	--	100	nA
IGSSR	Gate-body leakage Current, Reverse	$V_{GS}=-30\text{V}, V_{DS}=0\text{V}$	--	--	-100	nA

On Characteristics

$V_{GS(\text{th})}$	Date Threshold Voltage	$I_D=250\mu\text{A}, V_{DS}=V_{GS}$	3	--	5	V
$R_{DS(\text{on})}$	Static Drain-Source On-Resistance	$I_D=1.5\text{A}, V_{GS}=10\text{V}$	--	--	5	Ω

Dynamic Characteristics

Ciss	Input Capacitance	VDS=25V, VGS=0, f=1.0MHz	--	530	690	pF
Coss	Output Capacitance		--	57	75	pF
Crss	Reverse Transfer Capacitance		--	7	9	pF

Switching Characteristics

Td(on)	Turn-On Delay Time	VDD=400V, ID=3A RG=25 Ω (Note 3,4)	--	15	40	nS
Tr	Turn-On Rise Time		--	40	90	nS
Td(off)	Turn-Off Delay Time		--	30	70	nS
Tf	Turn-Off Fall Time		--	30	70	nS
Qg	Total Gate Charge	VDS=640, VGS=10V, ID=3A (Note 3,4)	--	15	19	nC
Qgs	Gate-Source Charge		--	3.5	--	nC
Qgd	Gate-Drain Charge		--	7.7	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	3	A	
I_{SM}	Maximum Plused Drain-Source DiodeForward Current	--	--	12	A	
V_{SD}	Drain-Source Diode Forward Voltage	$I_D=3\text{A}$	--	--	1.4	V
trr	Reverse Recovery Time	$I_S=3\text{A}, V_{GS}=0\text{V}$ $dI_F/dt=100\text{A}/\mu\text{s}$ (Note3)	--	180	--	nS
Qrr	Reverse Recovery Charge		--	0.72	--	μC

*Notes 1, L=66.7mH, IAS=3.0A, VDD=50V, RG=25 Ω , Starting TJ = 25°C

2, Repetitive Rating : Pulse width limited by maximum junction temperature

3, Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

4, Essentially Independent of Operating Temperature

Typical Characteristics

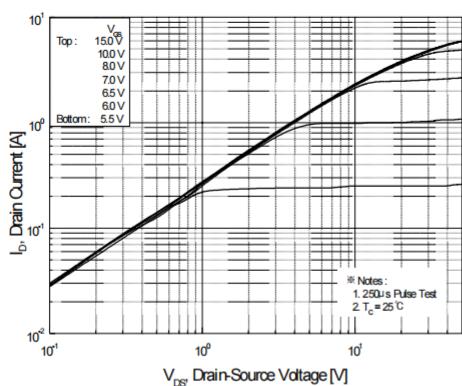


Figure 1. On-Region Characteristics

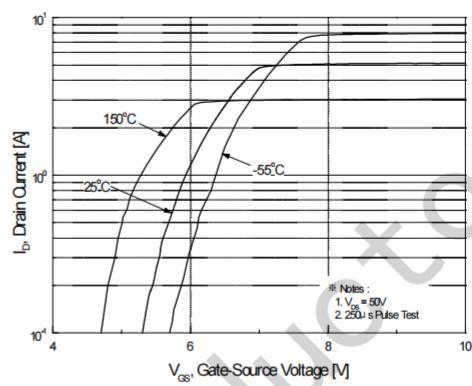


Figure 2. Transfer Characteristics

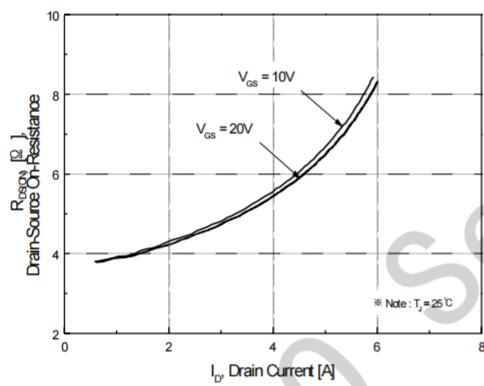


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

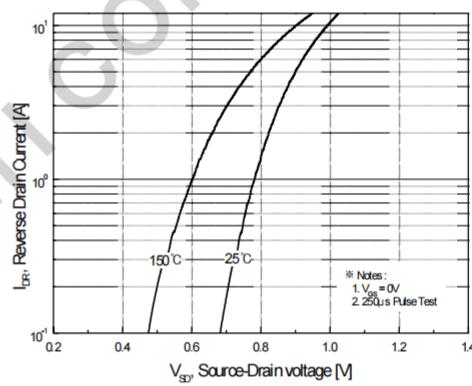


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

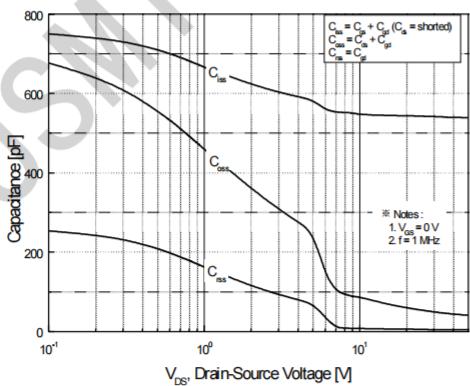


Figure 5. Capacitance Characteristics

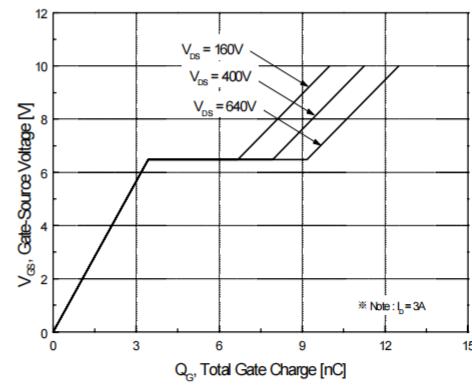


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

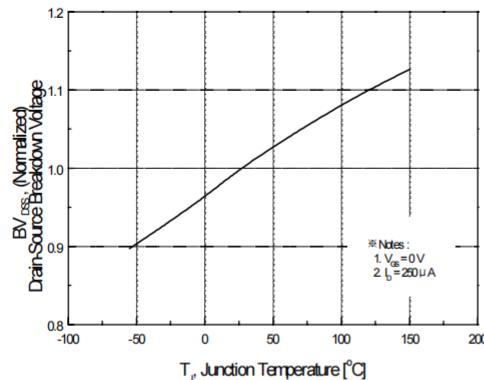


Figure 7. Breakdown Voltage Variation vs Temperature

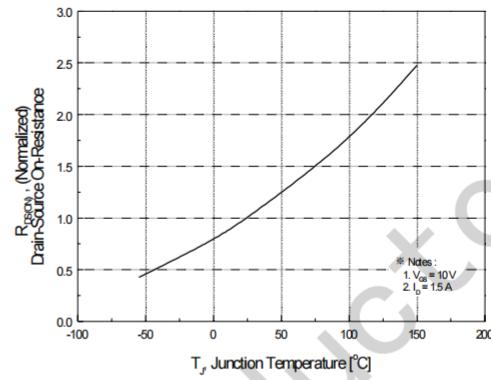


Figure 8. On-Resistance Variation vs Temperature

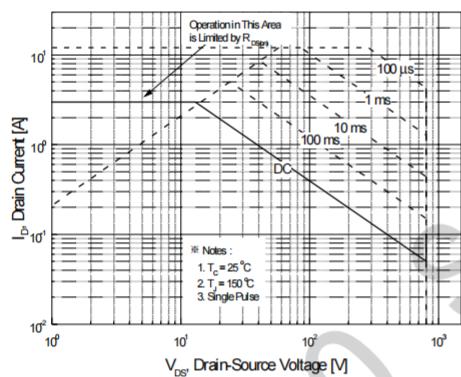


Figure 9-2. Maximum Safe Operating Area for WGF3N80

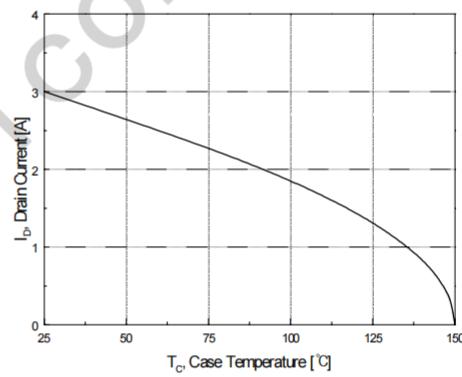


Figure 10. Maximum Drain Current vs Case Temperature

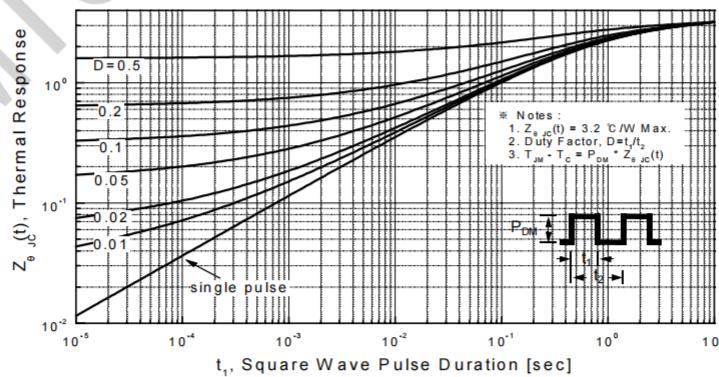
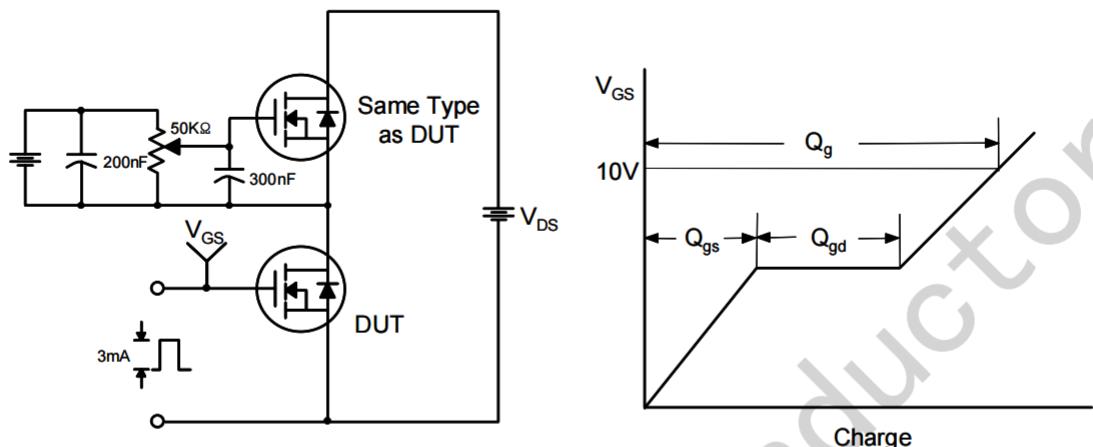
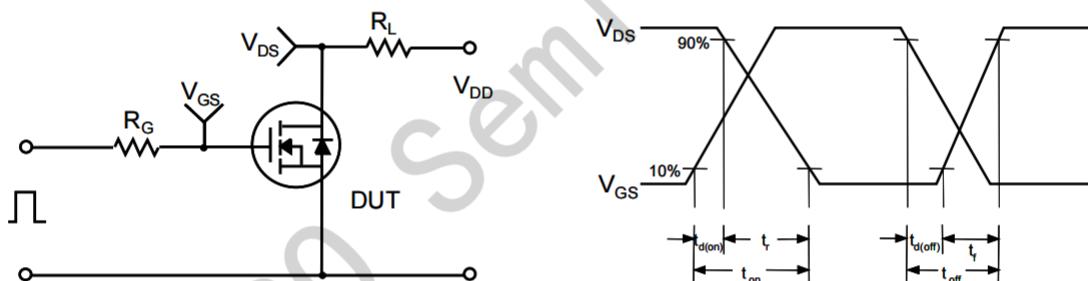


Figure 11-2. Transient Thermal Response Curve for WGF3N80

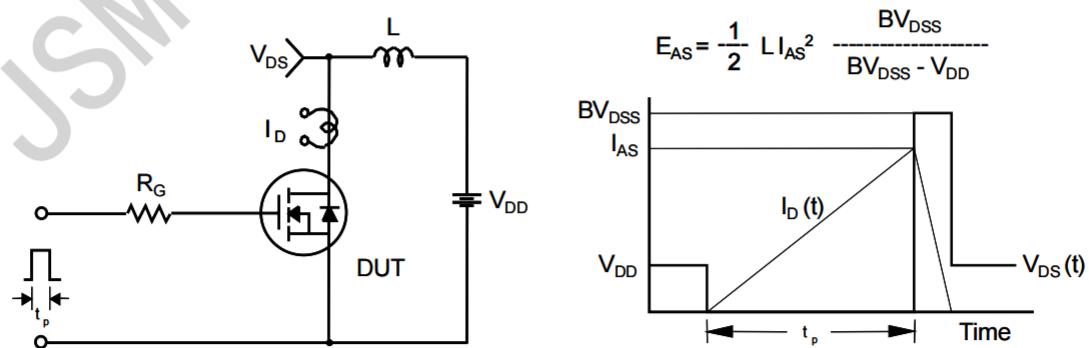
Gate Charge Test Circuit & Waveform



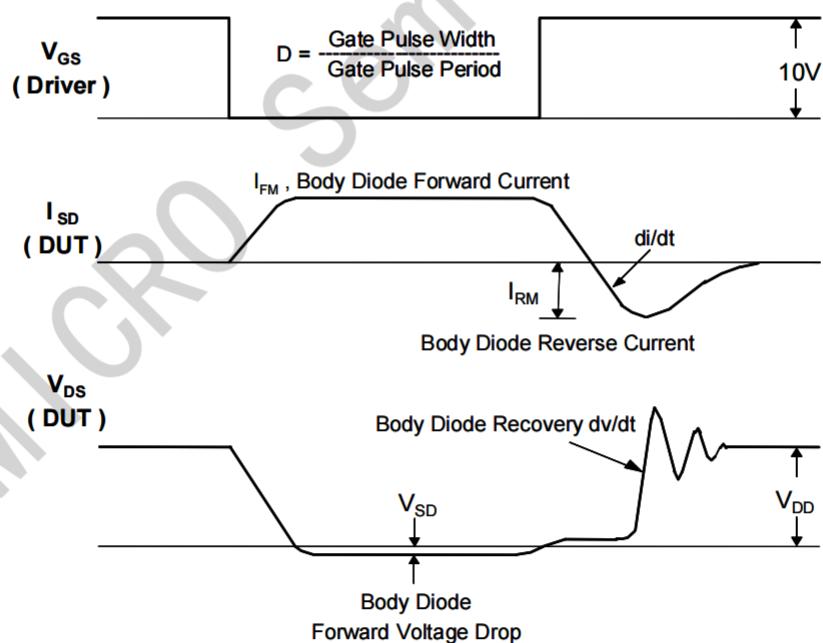
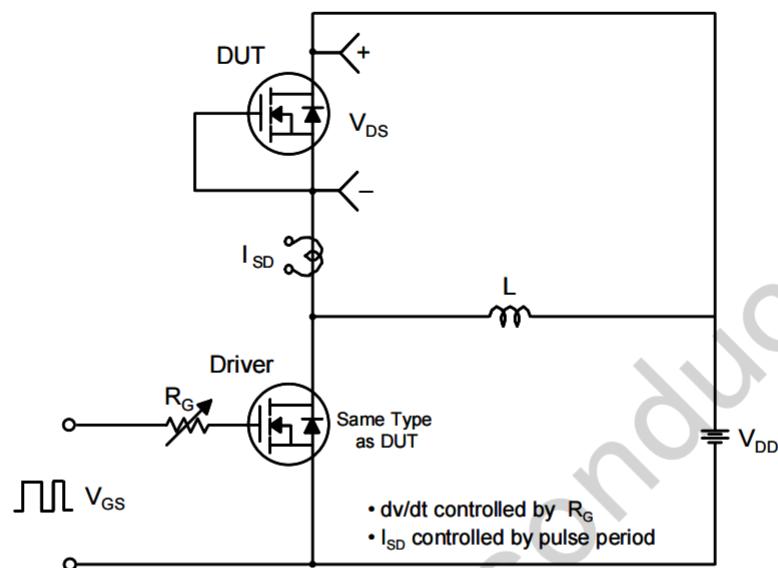
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms



Package Information

TO-220F

Dimensions in Millimeters

